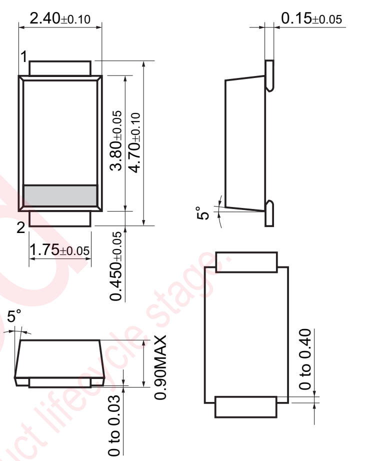
MA24D50

Silicon epitaxial planar type

For rectification



Marking Symbol: 5R

■ Features

- Forward current (Average) $I_{F(AV)}$ = 3.0 A rectification is possible
- Low forward voltage V_F

■ Absolute Maximum Ratings T_a = 25°C

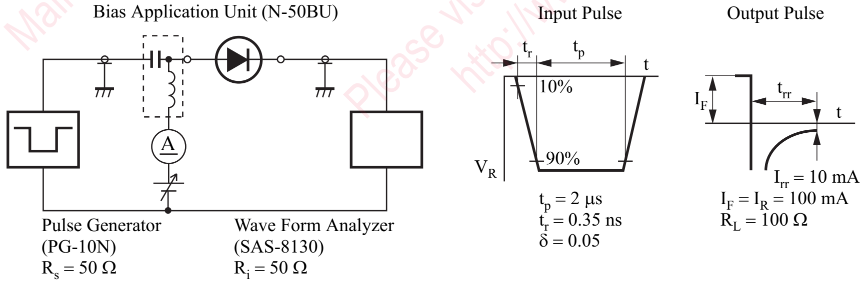
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average) *1	$I_{F(AV)}$	3.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	60	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–40 to +150	°C

Note) *1: Mounted on an alumina PC board
*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics T_a = 25°C±3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 3.0 A		0.46	0.51	V
Reverse current	I_R	V_R = 40 V		40	200	μA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		105		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA, I_{rr} = 10 mA, R_L = 100 Ω		33		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. *: t_{rr} measurement circuit



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 Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

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